

## PMP9367 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
I PCB1	1		PMP9367	Any	Printed Circuit Board	
C1, C2, C3	3	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1206	1206
C4, C7, C8, C9, C14, C18	6	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0402	0402
C5	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603
C6	1	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603
C10, C13, C16, C17	4	22uF	JMK212BJ226KG-T	Taiyo Yuden	CAP, CERM, 22uF, 6.3V, +/-10%, X5R, 0805	0805
C11	1	820pF	C1005C0G1E821J	TDK	CAP, CERM, 820pF, 25V, +/-5%, C0G/NP0, 0402	0402
C12, C15	2	100uF	JMK316BJ107ML-T	Taiyo Yuden	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1206	1206
Dbst	1	0.53V	30BQ040TRPBF	International Rectifier	Diode, Schottky, 40V, 3A, SMC	SMC
E1, E2	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
J1, J2	2					eg: 0603, used in PnP report
L1	1	10uH	7443331000	Würth Elektronik	Inductor, Shielded Drum Core, Ferrite, 10uH, 8A, 0.0207 ohm, SMD	Inductor, 10.9x9.3x10mm
Q1, Q2	2	100V	BSC123N10LS G	Infineon Technologies	MOSFET, N-CH, 100V, 71A, PG-TDSON-8	PG-TDSON-8
R2	1	226k	CRCW0402154KFKED	Vishay-Dale	RES, 154k ohm, 1%, 0.063W, 0402	0402
R4	1	1.76k	RT0805BRD071K76L	Yageo America	RES, 1.76k ohm, 0.1%, 0.125W, 0805	0805
R5	1	73.2k	CRCW040273K2FKED	Vishay-Dale	RES, 73.2k ohm, 1%, 0.063W, 0402	0402
R6	1	0.2	CRCW06030000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	0603
R7	1	24.3k	CRCW040224K3FKED	Vishay-Dale	RES, 24.3k ohm, 1%, 0.063W, 0402	0402
R8, R9, R10	3	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0k ohm, 1%, 0.063W, 0402	0402
U1	1		LM3150MH	Texas Instruments	SIMPLE SWITCHER® CONTROLLER, 42V Synchronous Step-Down, 14-pin TSSOP-EP	MXA14A
U2	1		TPS2561ADRC	Texas Instruments	DUAL CHANNEL PRECISION ADJUSTABLE CURRENT-LIMITED POWER SWITCHES, DRC0010A	DRC0010A
U3	1		TPS2513DBV	Texas Instruments	DUAL CHANNEL AUTO DETECT USB CHARGING CONTROLLER, DBV0006A	DBV0006A
VI+, VI-	2		3125-2-00-34-00-00-08-0	Mill-Max	PCB Pin, TH	PCB Pin (3125-2)
Cac, Cr	0	0.01uF	C1005X7R1E103K	TDK	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402
R1, R3	0	DNP	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
Rr	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402

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